



General Description

The SJD40P125 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

Features

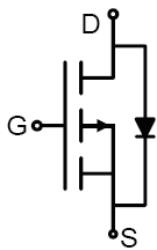
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

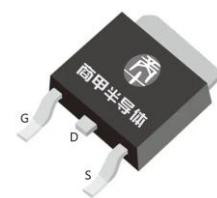
- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	-40	V
$R_{DS(ON)}_{TYP}$	14	mΩ
I_D	-39	A
Q_G	60	nC



Schematic Diagram



TO-252(DPAK) top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD40P125	SJD40P125	TO-252	Tape	\	\	2500 Pcs

Table 1. Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0\text{V}$)	-40	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0\text{V}$)	± 20	V
I_D	Drain Current-Continuous($T_c=25^\circ\text{C}$)	-39	A
	Drain Current-Continuous($T_c=100^\circ\text{C}$)	-25	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-156	A
P_D	Maximum Power Dissipation($T_c=25^\circ\text{C}$)	46	W
	Maximum Power Dissipation($T_c=100^\circ\text{C}$)	18.5	W
E_{AS}	Avalanche energy (Note 2)	182	mJ
T_J , T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{θJC}$	Thermal Resistance, Junction-to-Case		2.7	°C/W



40V P-Channel Trench Power MOSFET

Table 3. Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V} T_J=25^\circ\text{C}$			-1	μA
		$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V} T_J=125^\circ\text{C}$			-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1		-2.5	V
g_{FS}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-20\text{A}$		38		S
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A} T_J=25^\circ\text{C}$		14	17.5	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-15\text{A} T_J=25^\circ\text{C}$		18.2	24.2	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$		2320		pF
C_{oss}	Output Capacitance			174		pF
C_{rss}	Reverse Transfer Capacitance			147		pF
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, f=1.0\text{MHz}$		8.5		Ω
Switching Parameters						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-20\text{V}, R_L=1\Omega, R_{\text{GEN}}=3\Omega$		10		nS
t_r	Turn-on Rise Time			15		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			38		nS
t_f	Turn-Off Fall Time			16.4		nS
Q_g	Total Gate Charge	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-20\text{A}$		60		nC
Q_{gs}	Gate-Source Charge			8.5		nC
Q_{gd}	Gate-Drain Charge			13		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				-39	A
V_{SD}	Forward on Voltage (Note 3)	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-20\text{A}$			-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-20\text{A}, dI/dt=100\text{A}/\mu\text{s}$		17.3		ns
Q_{rr}	Reverse Recovery Charge	$I_F=-20\text{A}, dI/dt=100\text{A}/\mu\text{s}$		9.5		nC

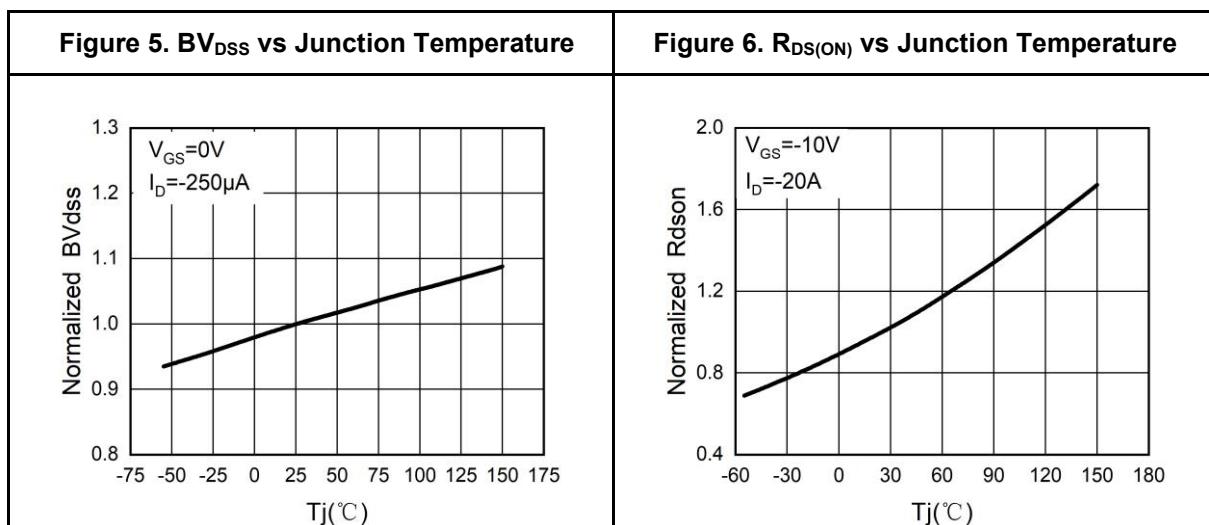
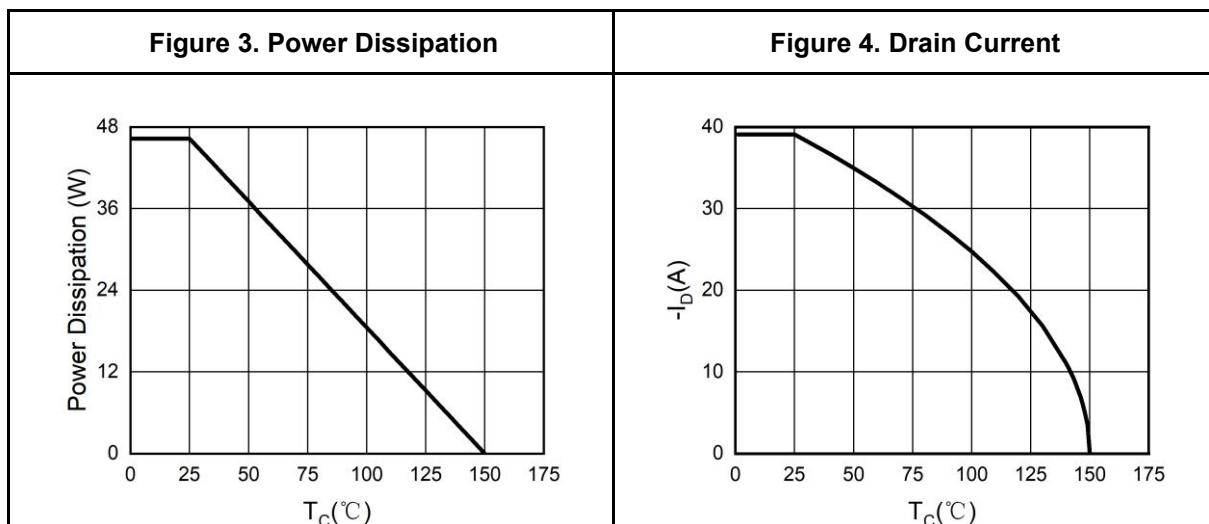
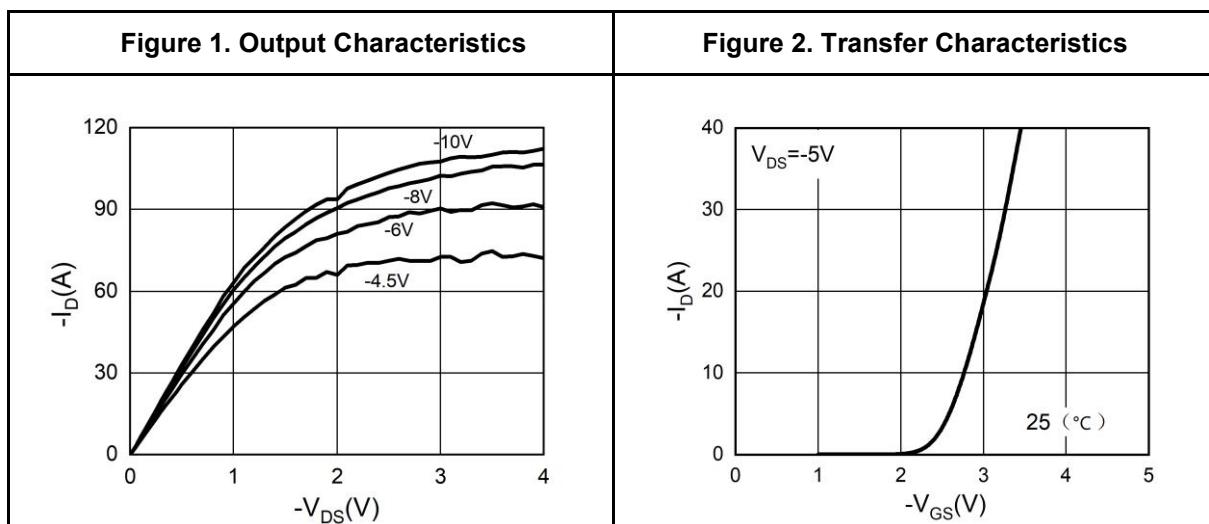
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E_{AS} condition: $T_J=25^\circ\text{C}, V_{\text{DD}}=40\text{V}, V_G=-10\text{V}, R_g=25\Omega, L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

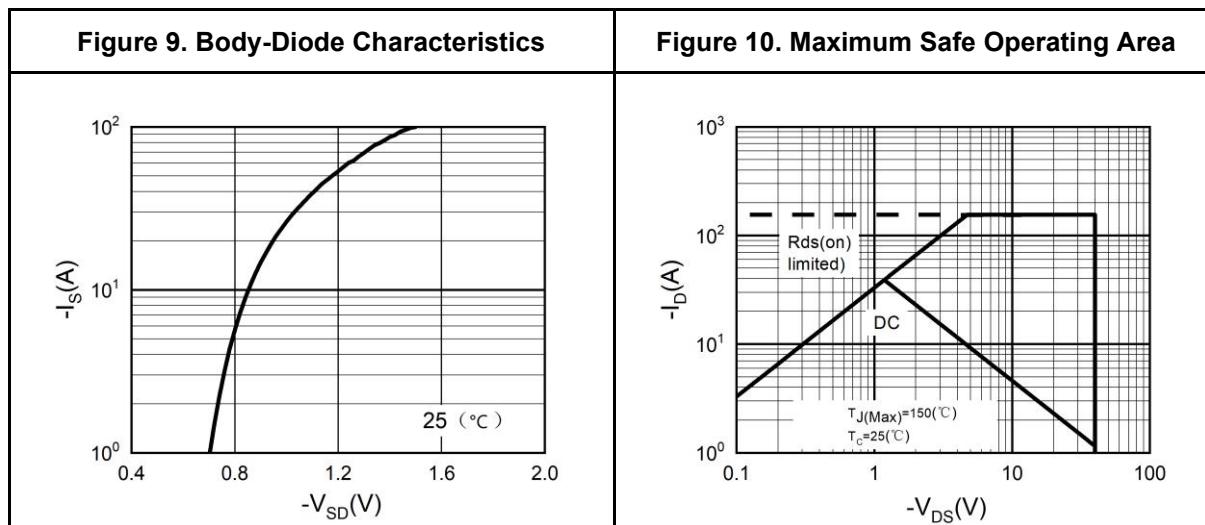
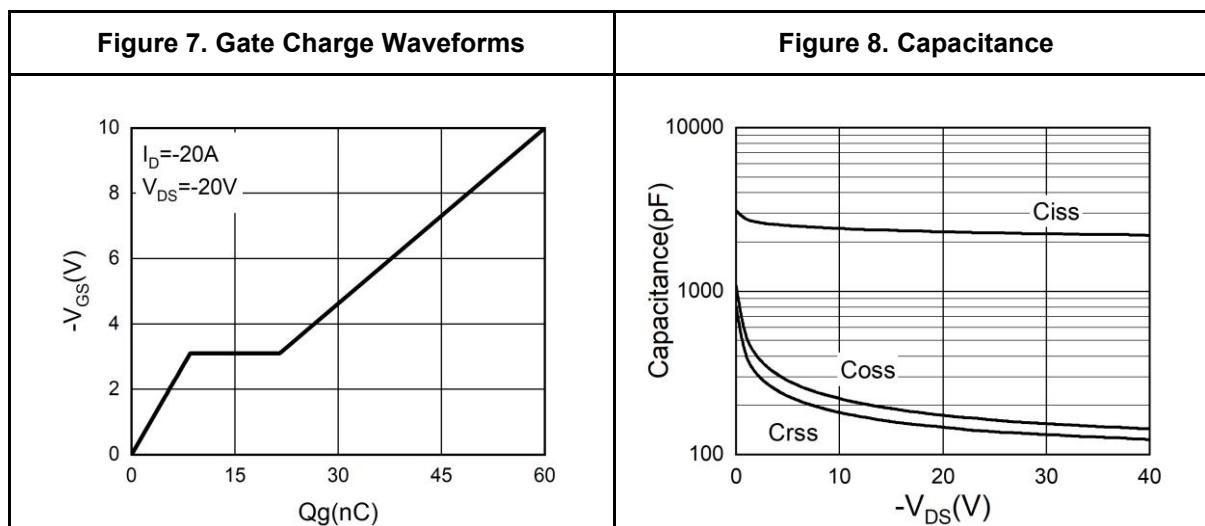


Typical Electrical And Thermal Characteristics (Curves)



40V P-Channel Trench Power MOSFET

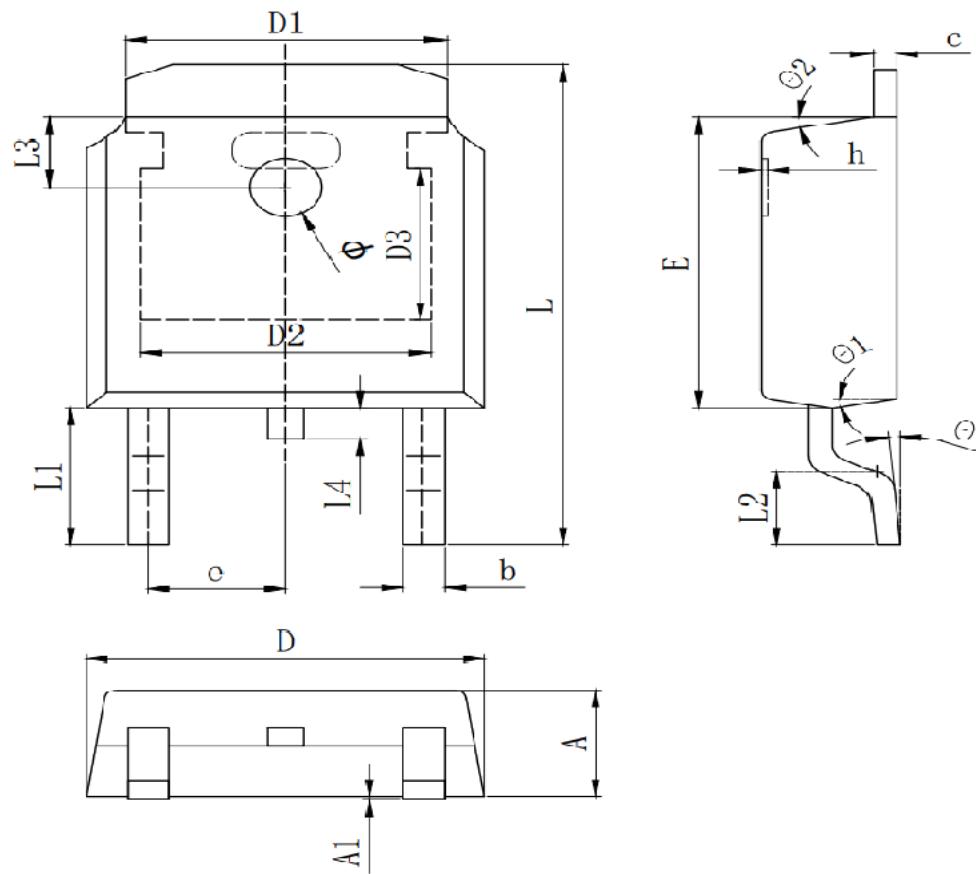
Typical Electrical And Thermal Characteristics (Curves)





40V P-Channel Trench Power MOSFET

TO-252 Package Information



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1		5.334 REF	
D2		4.826 REF	
D3		3.166 REF	
E	6.000	6.100	6.200
e		2.286 TYP	
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1		2.888 REF	
L2	1.400	1.550	1.700
L3		1.600 REF	
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ1		9° TYP	
θ2		9° TYP	



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This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Linde Semiconductor.

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